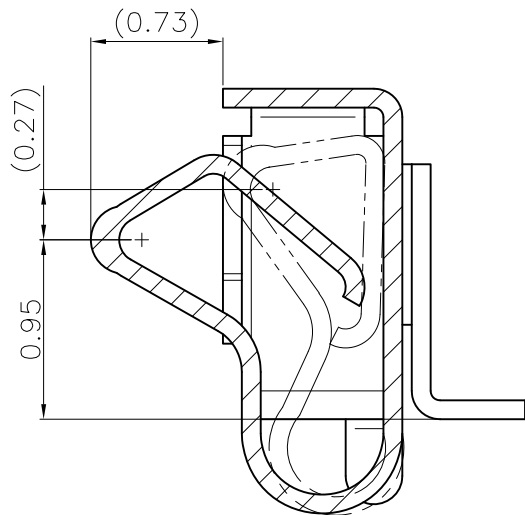
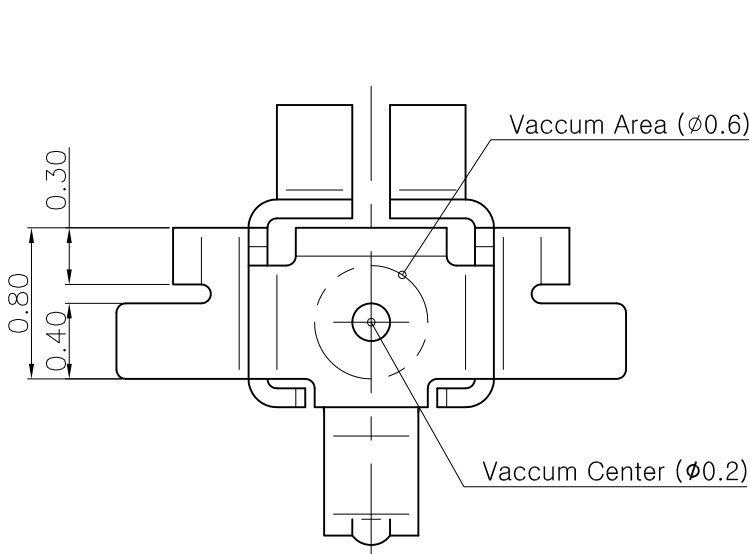
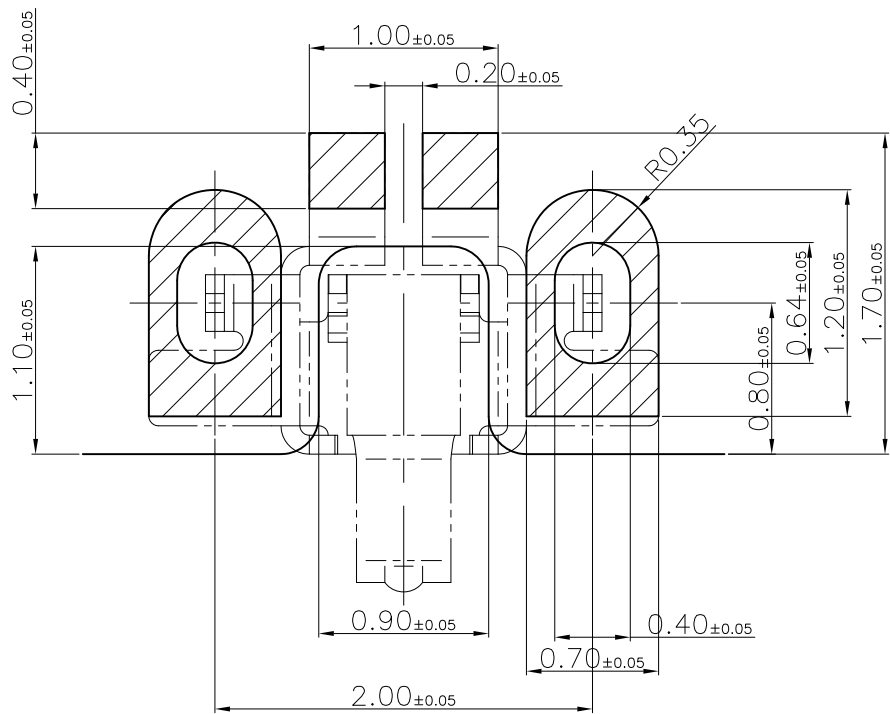
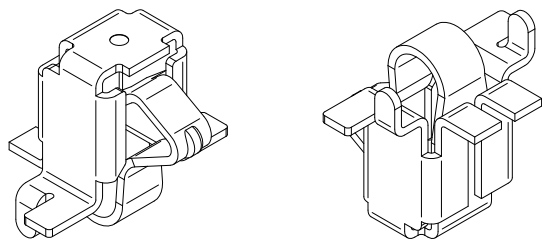




SIMULATION

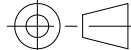


RECOMMENDED PCB LAYOUT(Bottom View)



*NOTE

- PLATING
 - Contact Area : Au 0.05 μ m Min. over Pd-Ni 0.2 μ m Min. over Ni 1.5~4.0 μ m.
 - SMD Area : Au 0.05 μ m Min over Ni 1.5~4.0 μ m.
 - Other Area : Ni 1.5~3.5 μ m.
- ☆: C.T.Q
- Contact 가동거리 : 0.73mm
권장 Contact 높이 : 가동거리의 50~96% 범위 내
(0.37~0.69mm) => (0.98~1.31mm)

1	Contact	Ti-Cu			Note.1		t0.1		
No	Part name	Material			Finish		Remarks		
General Tolerance		Scale	N/S	Units	mm		TITLE	CS-103A SIDE CONTACT	
Dimension	mm (°)	Date	2016. 03. 18						
X	± 0.2	Drawn	Design	Checked	Reviewed				Approved
X.X	± 0.15	J.H.Cho			Y.J. Park				S.K. Hong
X.XX	± 0.1	2016.03.16		-	2016.03.16	2016.03.16	SW No.	RI-CS-103A-A1.DWG	
X.XXX	± 0.05	 협진커넥터(주) HYUPJIN CONNECTOR Co.,Ltd.							
ANGLE	± 2°								
						Sheet	DWG No.	CS-103A-A1	
						1 of 1			